

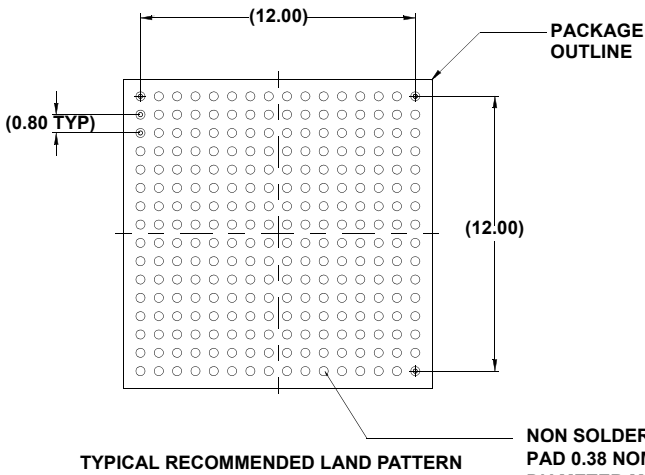
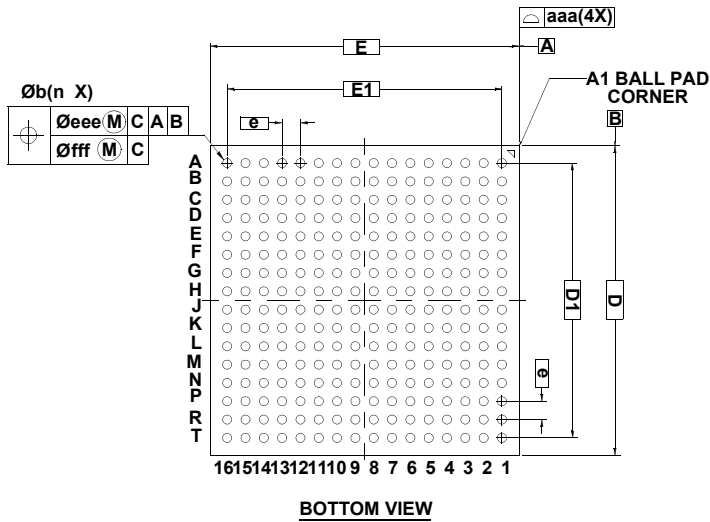
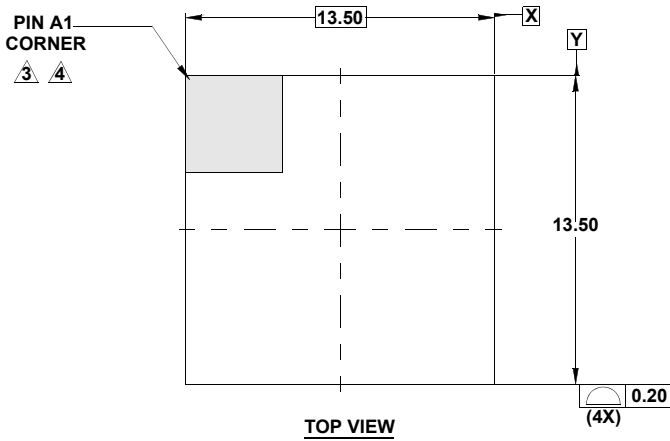
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

V256.13.5x13.5

256 LOW PROFILE, FINE PITCH PLASTIC BALL GRID ARRAY PACKAGE (LFBGA)

Rev 0, 3/13



NON SOLDER MASK DEFINED  
PAD 0.38 NOM/0.40mm  
DIAMETER MAX.

	SYMBOL	COMMON DIMENSIONS		
		MIN	NOM	MAX
Package		LFBGA		
Body Size	X	E		
	Y	D		
Ball Pitch	e	0.800		
Total Thickness	A	-	-	1.700
Mold Thickness	M	0.700 Ref.		
Substrate Thickness	S	0.560 Ref.		
Ball Diameter		0.400		
Stand Off	A1	0.270	-	0.370
Ball Width	b	0.380	-	0.480
Package Edge Tolerance	aaa	0.150		
Mold Parallelism	bbb	0.200		
Coplanarity	ddd	0.120		
Ball Offset (Package)	eee	0.150		
Ball Offset (Ball)	fff	0.080		
Ball Count	n	256		
Edge Ball Center to Center	X	E1	12.000	
	Y	D1	12.000	

